



Atty. Dkt. No. APPM/007761/IMPLANT/CONDUCTIVE/JB1

In re Application of:  
Ito, et al.

Group Art Unit: 2823

Examiner: George R. Fourson, III

For: Ion Implantation Method,  
SOI Wafer Manufacturing  
Method and Ion Implanting  
System

**CERTIFICATE OF MAILING**  
**37 CFR 1.8**

I hereby certify that this correspondence is being deposited on August 22, 2005 with the United States Postal Service as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

August 22, 2005  
Date

Signature \_\_\_\_\_

In response to the Office Action dated April 20, 2005, having a shortened statutory period for response extended one month to expire on August 22, 2005, please enter this response and reconsider the claims pending in the application for reasons discussed below. The fee for the one month extension is included on a separate sheet. Although Applicants believe that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/007761/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

**Amendments to the Specification** begin on page 2 of this paper. **Amendments to the Claims** are reflected in the listing of claims which begins on page 4 of this paper. **Amendments to the Drawings** begin on page 8 of this paper and include both an attached replacement sheet and an annotated sheet showing changes. **Remarks** begin on page 9 of this paper.